

Abstract

A resin composition for semiconductor encapsulation having good moldability, of which the cured product has effective electromagnetic wave shieldability, is provided. A resin
5 composition for semiconductor encapsulation, containing spherical sintered ferrite particles having the following properties (a) to (c): (a) the soluble ion content of the particles is at most 5 ppm; (b) the mean particle size of the particles is from 10 to 50 μm ; (c) the crystal structure of the particles
10 by X-ray diffractionometry is a spinel structure.